**Probe Horizon™**

Three-click wizard for:
- Fast and easy wafer loading
- Set contact quickly and safely
- Easy probe tip adjustment and planarization
- Minimizes probe and/or wafer damage

**Wizard-Style Dialog Boxes**
- Guided procedures for index setting, wafer and probe card theta alignments

**Customizable Quick Launch Bar**
- Quick access to most important applications, such as WaferMap, ControlCenter, Spectrum™ Vision System and WinCal XE™

**Control Center**
- Easy access to all navigation and control elements
- Docking function enables seamless integration into the windows desktop

**Start Menu**
- Windows-like quick-action start menu, making it easy to find functions and settings
- Lists most-used programs for quick start up

**Software Joystick**
- Intuitive navigation with digital or analogue operation
- Graphical position feedback, indicating exact location of current die on the wafer

**Programmable Position Buttons**
- Memorize user-defined positions referenced to either the user reference or zero position

**Z Control**
- Easy access to three programmed Z and chuck lift functions to place chuck at a safe height

**Second Navigation Tab**
- Provides secure interface for control of Z and theta movement
- Direct access to wafer handling functions, vacuum and wafer loading

**First Navigation Tab**
- Safe operation of the system by using programmed functions
- Pre-programmed positions prevent errors caused by accidental clicks

**Position Tracking**
- Easy to view the current position on the wafer

**WaferMap**
- Fully-customizable from single die to sub-die mapping, binning and other useful features
- Save maps in plain text format

**WaferMap Features**
- Integrated Z-profiling for accurate contact quality
- Multiple wafer view, fully enlarged
- Clustering for parallel testing > 2,000,000 die

**Status Bar**
- System status notifications confirm the measurement setup is correct and ready

**Image Analysis**
- Measuring function accurately measures the pad size, pad pitch and die size
- Snapshot function makes it easy to use images for documentation purposes

**Vision**
- Pattern recognition for automated wafer and die alignment
- Automation for index measurement, focusing and auxiliary site alignment

**Multi-View Layout**
- Select the layout of up to eight detailed zoom windows

**Multi-Camera Imaging**
- Up to four simultaneous live views for accurate probe tip placement

**CellView**
- Stitched image of the full IC for fastest on-screen navigation within the die

**Scope Follow Mode**
- Synchronizes the movement of the chuck and the microscope Z-axis

**Fully-Integrated Thermal Chuck Interface**
- Easy to control thermal chuck temperature from the software interface

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